



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260430000.2
Qualification of TI Clark as an additional wafer Probe Test site
and Assembly/Test site for select devices
Change Notification / Sample Request

Date: April 30, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260430000.2
Attachment: 1




Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM74900QRGERQ1	NULL
LM74910QRGERQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260430000.2		PCN Date:	April 30, 2026	
Title:	Qualification of TI Clark as an additional wafer Probe Test site and Assembly/Test site for select devices				
Customer Contact:	Change Management team		Dept:	Quality Services	
Proposed 1st Ship Date:	October 27, 2026		Sample requests accepted until:	June 29, 2026*	
*Sample requests received after June 29, 2026 will not be supported.					
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of TI Clark as an additional wafer Probe Test site and Assembly/Test site for select devices. No material differences between sites.					
	Current Site	Additional Site			
Assembly/Test site	TI CDAT	TI CLARK			
Wafer probe Test site	CD-PR	CLARK-PR			
Qual details are provided in the Qual Data Section.					
Reason for Change:					
Continuity of Supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
Review the SDP for full evaluation of the change based on the customer use case.					
Impact on Environmental Ratings					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
RoHS	REACH	Green Status	IEC 62474		
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change		
Changes to product identification resulting from this PCN:					
Assembly Site Information:					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
TI CDAT	CDA	CHN	Chengdu		
TI Clark	QAB	PHL	Pampanga		
Sample Product Shipping Label (not actual product label)					

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:
 ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO: USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

LM74900QRGERQ1	LM74910QRGERQ1
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Qualification Report

Automotive Qualification Summary

(As per AEC-Q100 Rev. J and JEDEC Guidelines)

LM749xxQRGERQ1 Assy and Test Offload
 Approve Date 03-March-2026

Product Attributes

Attributes	Qual Device:	QBS Package, Process, Product Reference:
	LM74910QRGERQ1	DRV889QRGERQ1
Automotive Grade Level	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125
Product Function	Power Management	Power Management
Water Fab Supplier	RFAB	RFAB
Assembly Site	CLARK-AT	CLARK-AT
Package Group	QFN	QFN
Package Designator	RGE	RGE
Pin Count	24	24

QBS: Qual By Similarity, also known as Generic Data
 Qual Device LM74910QRGERQ1 is qualified at MSL2 260C
 Qual Device LM74900QRGERQ1 is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device:	QBS Package, Process, Product Reference:
								LM74910QRGERQ1	DRV889QRGERQ1
Test Group A - Accelerated Environment Stress Tests									
PC	A1	JEDEC J-STD-020 JEDEC-A113	3	77	Preconditioning	MSL2 260C	-	-	3/1/10
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/23/0
ACU/HAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	3/23/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	3/23/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests									
Test Group C - Package Assembly Integrity Tests									
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/300	3/900
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/300	3/900
SD	C3	JEDEC J-STD-002	1	15	Pb-Free Solderability	>95% Lead Coverage	-	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	3/300

Test Group D - Die Fabrication Reliability Tests									
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDOB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests									
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	1/300

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2504-038

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-18, SEM-TF-01

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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